

Power MOSFET

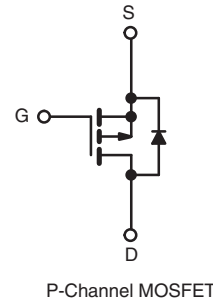
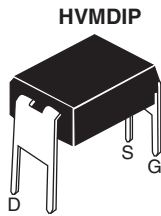
PRODUCT SUMMARY		
V _{DS} (V)	- 100	
R _{DS(on)} (Ω)	V _{GS} = - 10 V	1.0
Q _g (Max.) (nC)	8.7	
Q _{gs} (nC)	2.2	
Q _{gd} (nC)	4.1	
Configuration	Single	

FEATURES

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- For Automatic Insertion
- End Stackable
- P-Channel
- 175 °C Operating Temperature
- Fast Switching
- Compliant to RoHS Directive 2002/95/EC



Available
RoHS*
COMPLIANT

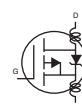
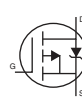


ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	- 100	V	
Gate-Source Voltage		V _{GS}	± 20		
Continuous Drain Current	V _{GS} at - 10 V	I _D	T _A = 25 °C	- 0.70	A
			T _A = 100 °C	- 0.49	
Pulsed Drain Current ^a		I _{DM}	- 5.6		
Linear Derating Factor			0.0083	W/°C	
Single Pulse Avalanche Energy ^b		E _{AS}	140	mJ	
Repetitive Avalanche Current ^a		I _{AR}	- 0.7	A	
Repetitive Avalanche Energy ^a		E _{AR}	0.13	mJ	
Maximum Power Dissipation	T _A = 25 °C	P _D	1.3	W	
Peak Diode Recovery dV/dt ^c		dV/dt	- 5.5	V/ns	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature)	for 10 s		300 ^d		

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- V_{DD} = - 25 V, starting T_J = 25 °C, L = 52 mH, R_g = 25 Ω, I_{AS} = - 2.0 A (see fig. 12).
- I_{SD} ≤ - 4.0 A, dI/dt ≤ 75 A/μs, V_{DD} ≤ V_{DS}, T_J ≤ 175 °C.
- 1.6 mm from case.

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	120	°C/W

SPECIFICATIONS ($T_J = 25\text{ °C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$		- 100	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C , $I_D = -1\text{ mA}$		-	- 0.091	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$		- 2.0	-	- 4.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20\text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}$		-	-	- 100	μA
		$V_{DS} = -80\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ °C}$		-	-	- 500	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = -10\text{ V}$	$I_D = -0.42\text{ A}^b$	-	1.0	-	Ω
Forward Transconductance	g_{fs}	$V_{DS} = -50\text{ V}, I_D = -0.42\text{ A}$		0.60	-	-	S
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V},$ $V_{DS} = -25\text{ V},$ $f = 1.0\text{ MHz}$, see fig. 5		-	200	-	pF
Output Capacitance	C_{oss}			-	94	-	
Reverse Transfer Capacitance	C_{rss}			-	18	-	
Total Gate Charge	Q_g	$V_{GS} = -10\text{ V}$	$I_D = -4.0\text{ A}, V_{DS} = -80\text{ V}$ see fig. 6 and 13 ^b	-	-	8.7	nC
Gate-Source Charge	Q_{gs}			-	-	2.2	
Gate-Drain Charge	Q_{gd}			-	-	4.1	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -50\text{ V}, I_D = -4.0\text{ A}$ $R_g = 24\text{ }\Omega, R_D = 11\text{ }\Omega,$ see fig. 10 ^b		-	10	-	ns
Rise Time	t_r			-	27	-	
Turn-Off Delay Time	$t_{d(off)}$			-	15	-	
Fall Time	t_f			-	17	-	
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact 		-	4.0	-	nH
Internal Source Inductance	L_S			-	6.0	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	- 0.70	A
Pulsed Diode Forward Current ^a	I_{SM}			-	-	- 5.6	
Body Diode Voltage	V_{SD}	$T_J = 25\text{ °C}, I_S = -0.7\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	- 5.5	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ °C}, I_F = -4.0\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$		-	82	160	ns
Body Diode Reverse Recovery Charge	Q_{rr}			-	0.15	0.30	μC

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

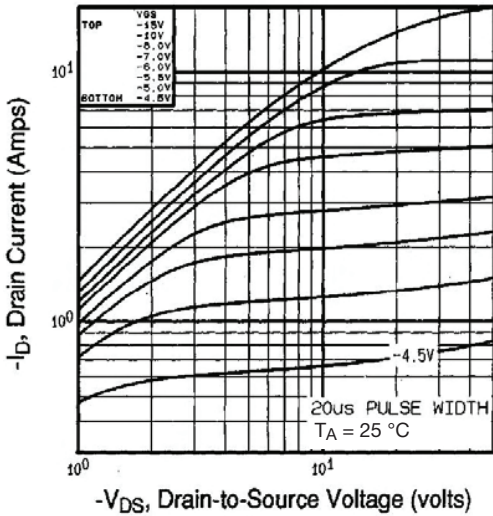


Fig. 1 - Typical Output Characteristics, $T_A = 25\text{ }^\circ\text{C}$

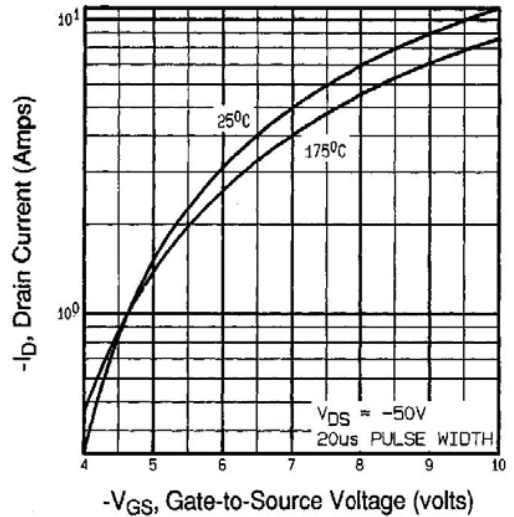


Fig. 3 - Typical Transfer Characteristics

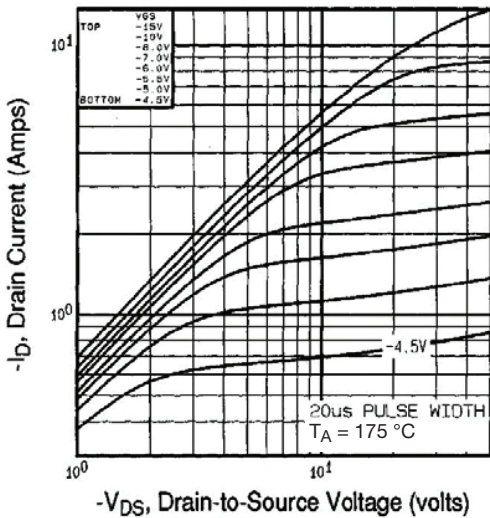


Fig. 2 - Typical Output Characteristics, $T_A = 175\text{ }^\circ\text{C}$

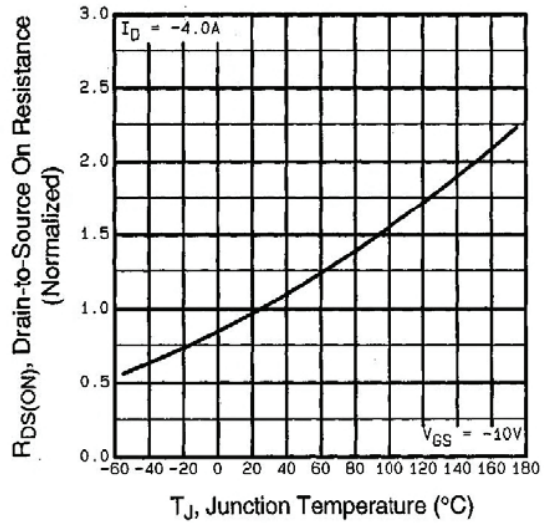


Fig. 4 - Normalized On-Resistance vs. Temperature

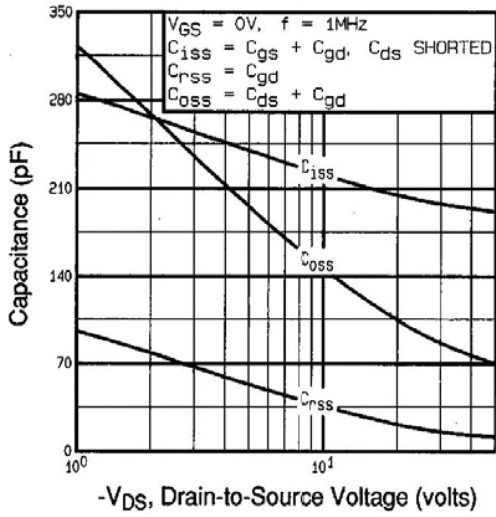


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

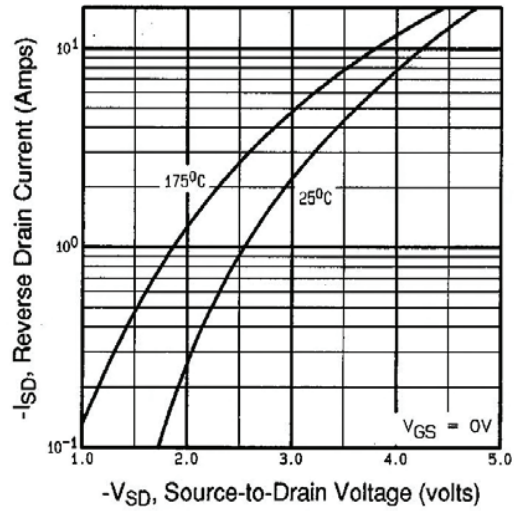


Fig. 7 - Typical Source-Drain Diode Forward Voltage

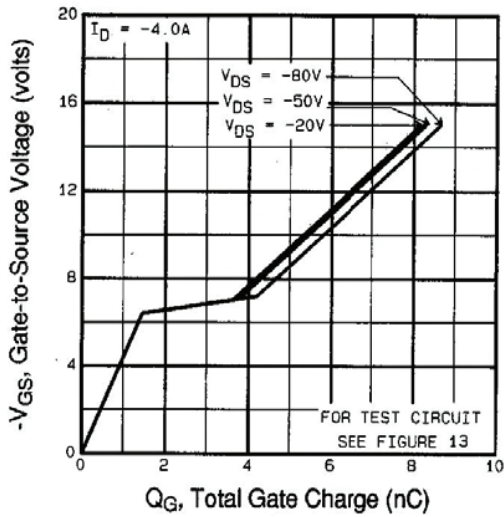


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

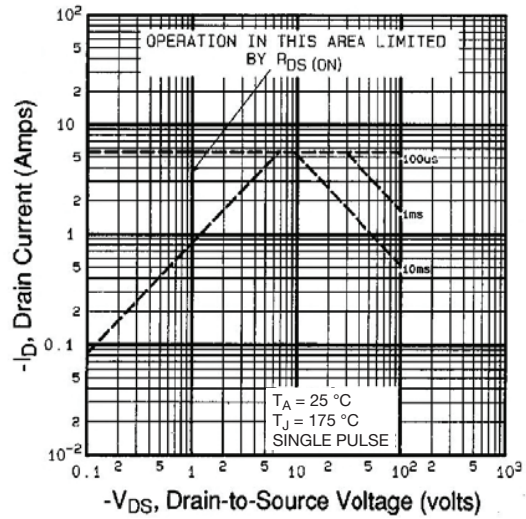


Fig. 8 - Maximum Safe Operating Area

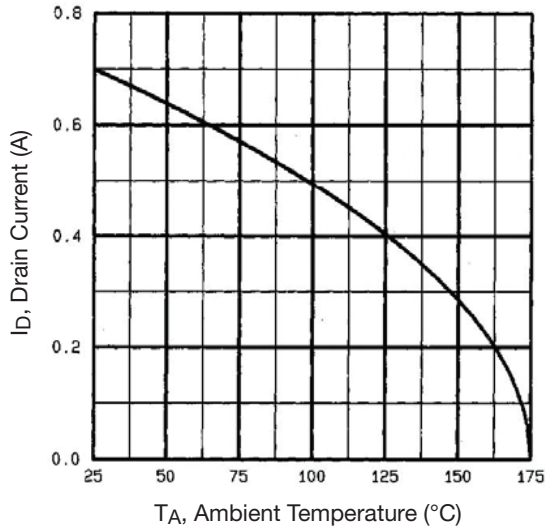


Fig. 9 - Maximum Drain Current vs. Ambient Temperature

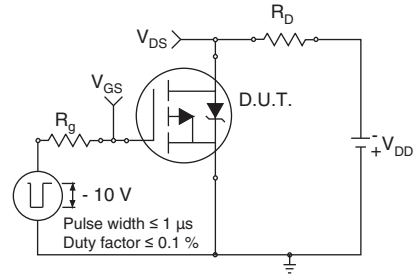


Fig. 10a - Switching Time Test Circuit

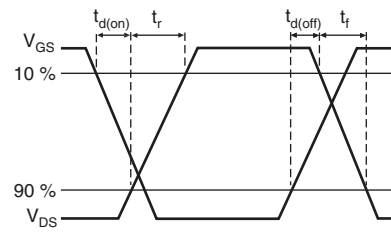


Fig. 10b - Switching Time Waveforms

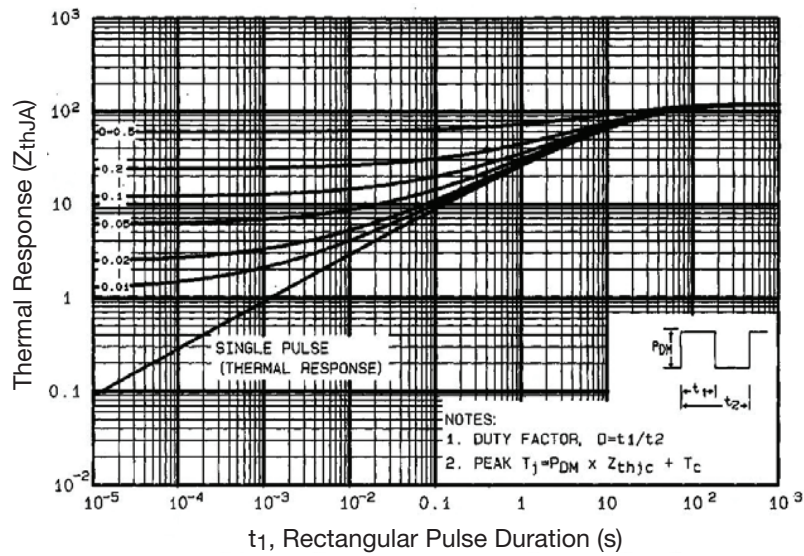


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

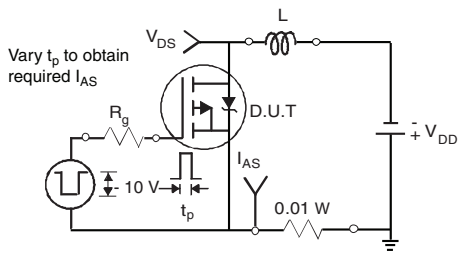


Fig. 12a - Unclamped Inductive Test Circuit

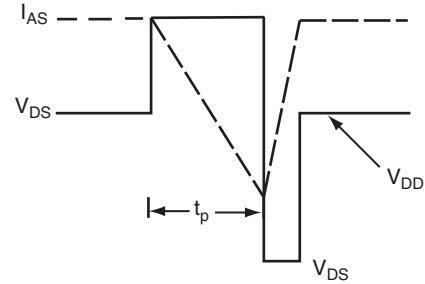


Fig. 12b - Unclamped Inductive Waveforms

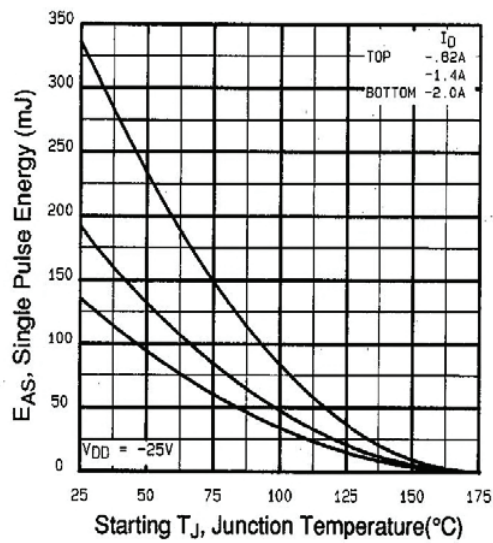


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

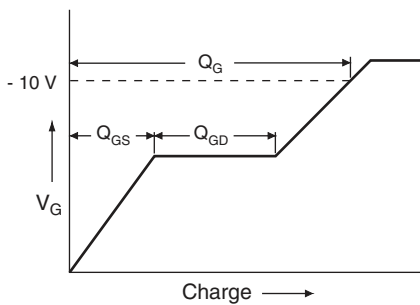


Fig. 13a - Basic Gate Charge Waveform

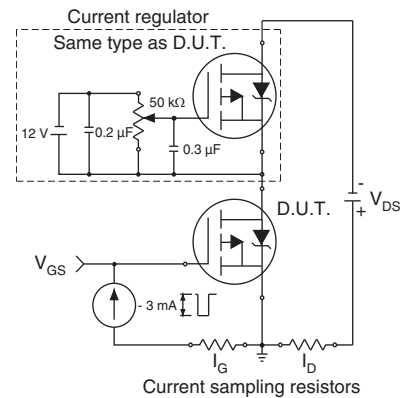
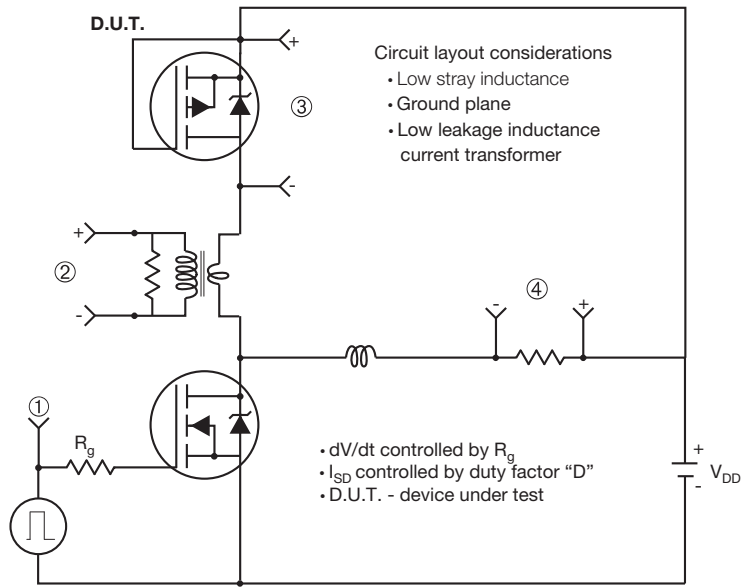
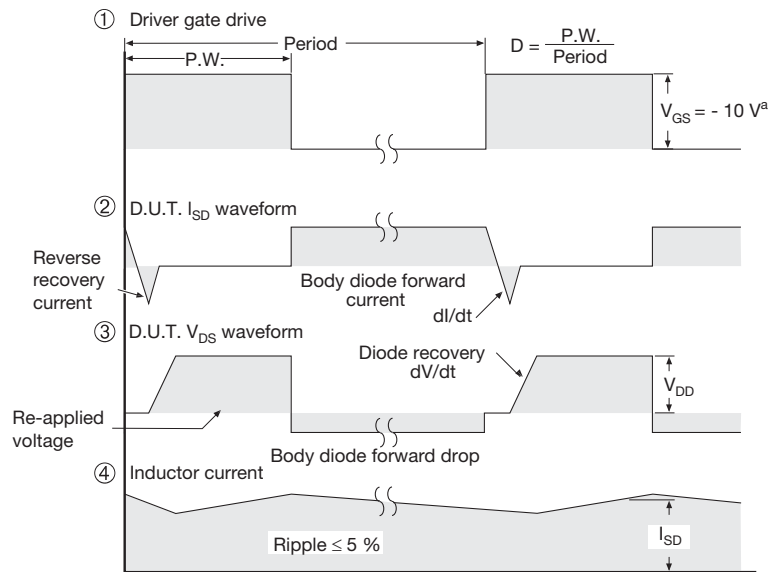


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



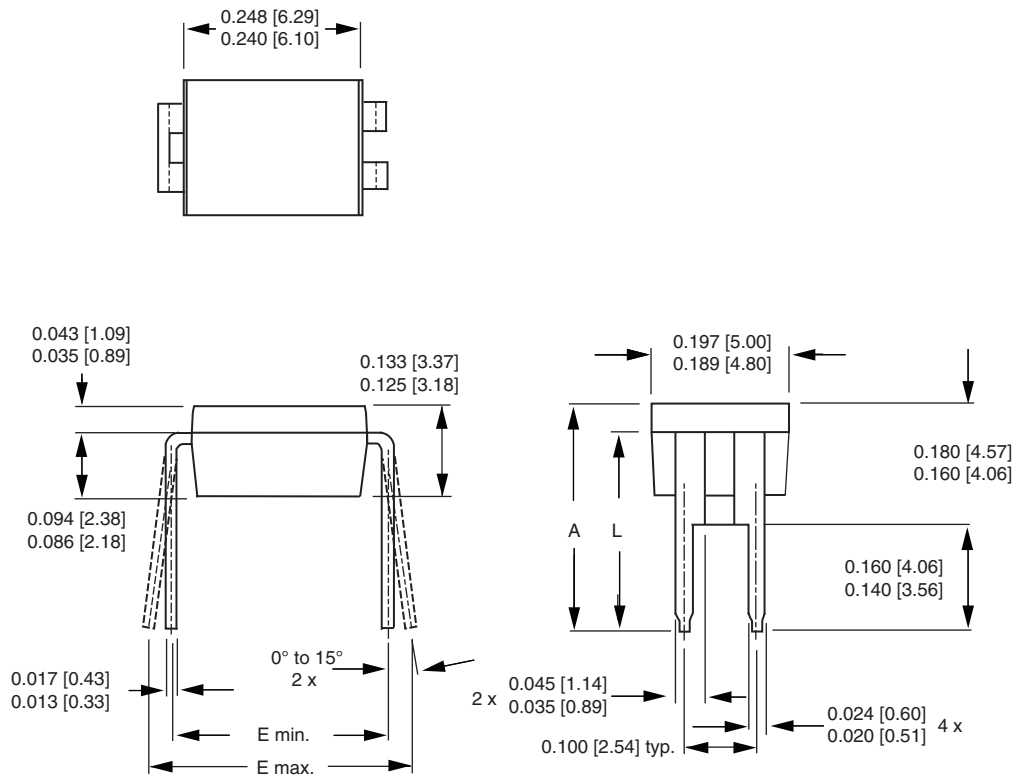
Note
• Compliment N-Channel of D.U.T. for driver



Note
a. $V_{GS} = -5 V$ for logic level and $-3 V$ drive devices

Fig. 14 - For P-Channel

HVM DIP (High voltage)



DIM.	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.310	0.330	7.87	8.38
E	0.300	0.425	7.62	10.79
L	0.270	0.290	6.86	7.36

ECN: X10-0386-Rev. B, 06-Sep-10
DWG: 5974

Note

1. Package length does not include mold flash, protrusions or gate burrs. Package width does not include interlead flash or protrusions.

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